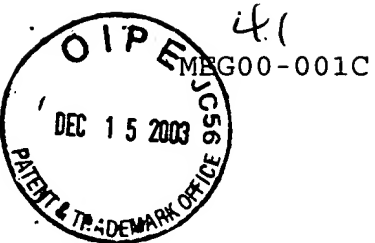


2841



December 2, 2003

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

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Subject:

Serial No.	09/684,519	10/10/00
JIN-YUAN LEE		
"A THERMALLY COMPLIANT PCB SUBSTRATE FOR THE APPLICATION OF CHIP SCALE PACKAGES"		
Grp. Art Unit: 2841	HUNG S. BUI	

RESPONSE PATENT OFFICE ACTION

Dear Sir:

In response to the Office Action dated October 2, 2003, please amend the above-identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on December 9, 2003.

Rosemary L. S. Pike. Reg # 39,332

Signature Rosemary L. S. Pike
Date Dec. 9, 2003

Amendments to the Claims are reflected in the listing of the Claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 20 of this paper.